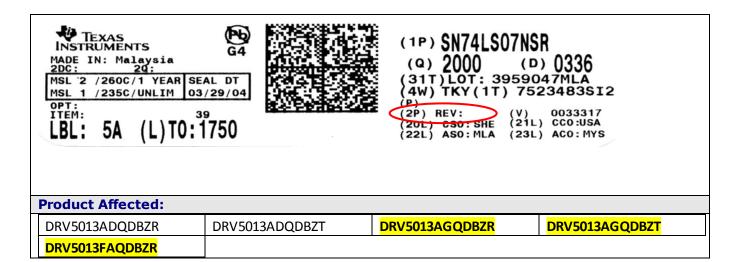
PCN Number: 2022			20722001.1 <mark>A</mark>					Date:	July 28, 2022			
				Process Technology and Die Chang				ange f				
Customer Contact:			PCN Manager				Dept:		Quality Services			
Proposed 1 <sup>st</sup> Ship Date:			Oct 22, 2022			Sample requests accepted until:			August 22, 2022*			
*Sa	*Sample requests received after August 22, 2022 will not be supported.											
Cha	nge Ty	/pe:										
	Asser	nbly Site		Assembly Process					Assembly Materials			
Design			Electrical Specification						nical Specification			
	Test Site			Packing/Shipping/Labeling					Test Process			
		r Bump Site				er Bump Material			Wafer Bump Process			
	Wafe	r Fab Site		Wafer Fab Materials					Wafer Fab Process			
					Part number change							
				N	otification	<u> Deta</u>	ails					
		n of Change:										
										cluded in the original product affected		
sect	ion bel	<mark>ow. For these</mark>	newly	added d	evices ONLY	, the e	expect	ed firs	t shipme	nt date for the new		
					this notice,	and s	ample	reque	<mark>sts will b</mark>	<mark>e accepted until 30</mark>		
		the date of th					_	_				
The	propos	ed 1 <sup>st</sup> ship da	te of C	october 2	2, 2022 still	applies	s for t	he orig	jinal set	of devices.		
Texas Instruments is pleased to announce the qualification of a new process technology (LBC9) in RFAB and die change as listed below in the product affected section.												
Fab Site C			Current Process Nev				/ Process					
			Technology			Technology						
RFAB			LBC8			LE	LBC9					
In support of the qualification of the new process technology, the devices will undergo a die change.												
Qual details are provided in the Qual Data Section.												
Rea	son fo	r Change:										
Continuity of supply												
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):												
None.												
Changes to product identification resulting from this PCN:												
The Die Revision will change as shown in the table and sample label below:												
Cur	Current New											
Die Rev [2P] Die R			lev [2P]									
	A1											

Sample product shipping label (not actual product label)



## Qualification Report Approve Date 22-July-2022

## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>DRV5013ADQDBZR</u>	QBS Reference: <u>TMAG5231B1DQDBZR</u>	
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	1/3/0	
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	
ESD	E2	ESD HBM	-	4000 Volts	1/3/0	1/3/0	
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	

• Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

• The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

• The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

• The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

# Qualification Report Approve Date 27-July-2022

## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>DRV5013AGQDBZR</u>	Qual Device: <u>DRV5013FAQDBZR</u>	QBS Reference: TMAG5231B1DQDBZR	QBS Reference: DRV5013ADQDBZR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	1/3/0	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	4000 Volts	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0

• Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

• The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

• The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

• The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2109-069

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail				
WW PCN Team	<u>PCN ww admin team@list.ti.com</u>				

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